

# SD57120

# RF POWER TRANSISTORS The *LdmoST* FAMILY

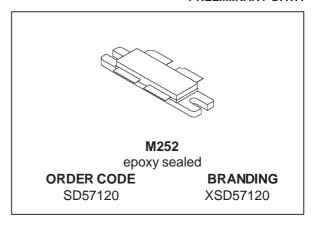
#### PRELIMINARY DATA

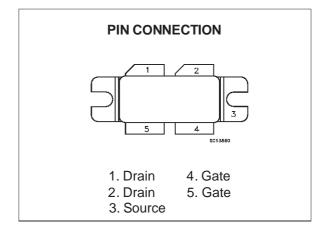
# N-CHANNEL ENHANCEMENT-MODE LATERAL MOSFETs

- EXCELLENT THERMAL STABILITY
- COMMON SOURCE CONFIGURATION, PUSH-PULL
- <sub>v</sub> P<sub>OUT</sub> = 120 W with 13 dB gain @ 960 MHz
- BeO FREE PACKAGE

#### **DESCRIPTION**

The SD57120 is a common source N-Channel enhancement-mode lateral Field-Effect RF power transistor designed for broadband commercial and industrial applications at frequencies up to 1.0 GHz. The SD57120 is designed for high gain and broadband performance operating in common source mode at 28V. Its internal matching makes it ideal for base station applications requiring high linearity.





#### ABSOLUTE MAXIMUM RATINGS (Tcase = 25 °C)

Symbol	Parameter	Value	Unit
V <sub>(BR)DSS</sub>	Drain Source Voltage	65	V
V <sub>GS</sub>	Gate-Source Voltage	± 20	V
I <sub>D</sub>	Drain Current	14	А
P <sub>DISS</sub>	Power Dissipation (@ Tc= 70°C)	236	W
Tj	Max. Operating Junction Temperature	200	°C
T <sub>STG</sub>	Storage Temperature	-65 to 150	°C

#### THERMAL DATA

	R <sub>th(j-c)</sub>	Junction-Case Thermal Resistance	0.55	°C/W
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## **ELECTRICAL SPECIFICATION** (T<sub>case</sub> = 25 °C)

## STATIC (Per Section)

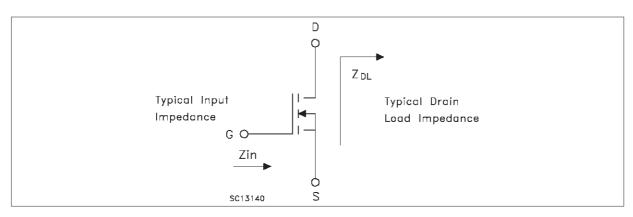
Symbol		Parameter		Min.	Тур.	Max.	Unit
V <sub>(BR)DSS</sub>	$V_{GS} = 0V$	$I_{DS} = 10 \text{ mA}$		65			V
I <sub>DSS</sub>	V <sub>GS</sub> = 0V	$V_{DS} = 28 \text{ V}$				1	μΑ
Igss	Vgs = 20V	V <sub>DS</sub> = 0 V				1	μА
$V_{GS(Q)}$	$V_{DS} = 28V$	$I_D = 100 \text{ mA}$		3.0		5.0	V
V <sub>DS(ON)</sub>	V <sub>GS</sub> = 10V	$I_D = 3 A$			0.7	0.8	V
G <sub>FS</sub>	V <sub>DS</sub> = 10V	I <sub>D</sub> = 3 A			3		mho
C <sub>ISS</sub> *	V <sub>GS</sub> = 0V	$V_{DS} = 28 V$	f = 1 MHz		175		pF
Coss	Vgs = 0V	V <sub>DS</sub> = 28 V	f = 1 MHz		44		pF
C <sub>RSS</sub>	V <sub>GS</sub> = 0V	V <sub>DS</sub> = 28 V	f = 1 MHz		1.7		pF

<sup>\*</sup> Includes Internal Input Moscap.

#### **DYNAMIC**

Symbol	Parameter				Min.	Тур.	Max.	Unit
Pout	$V_{DD} = 28V$ $f = 9$	960 MHz	$I_{DQ} = 80$	0 mA	120			W
G <sub>PS</sub>	V <sub>DD</sub> = 28 V P <sub>out</sub>	t = 120 W	$I_{DQ} = 80$	0 mA	13	14		dB
η <sub>D</sub>	$V_{DD} = 28 \text{ V}$ $P_{out}$	t = 120W	$I_{DQ} = 80$	0 mA	50			%
	$f = 960 \text{ MHz}  V_{DD}$ ALL PHASE ANGL	0 0 1	= 120 W	$I_{DQ} = 800 \text{ mA}$	10:1			VSWR

#### IMPEDANCE DATA



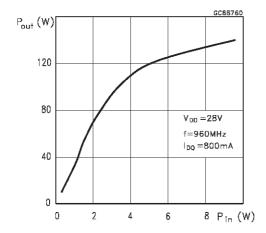
FREQ.	Z <sub>IN</sub> (Ω)	Z <sub>DL</sub> (Ω)
945 MHz	3.9 + j 4.9	3.6 - j 5.1
960 MHz	4.1 - j 4.6	3.24 - j 4.74
980 MHz	3.9 + j 5.2	3.27 - j 6.9

Measured gate to gate and drain to drain respectively.

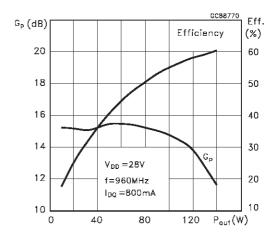
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#### TYPICAL PERFORMANCE

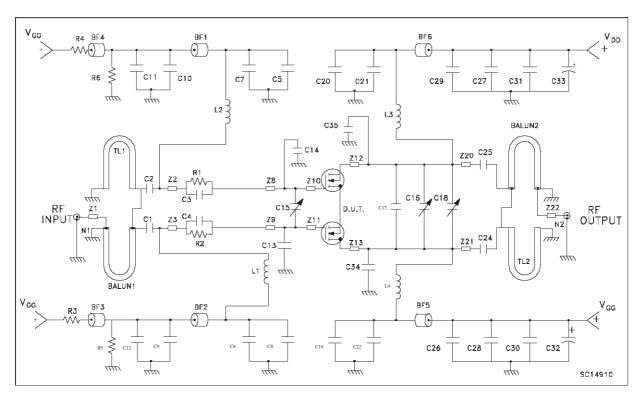
#### Output Power vs. Input Power



## Power Gain and Efficiency vs. Output Power



#### 960 MHz Test Circuit Schematic

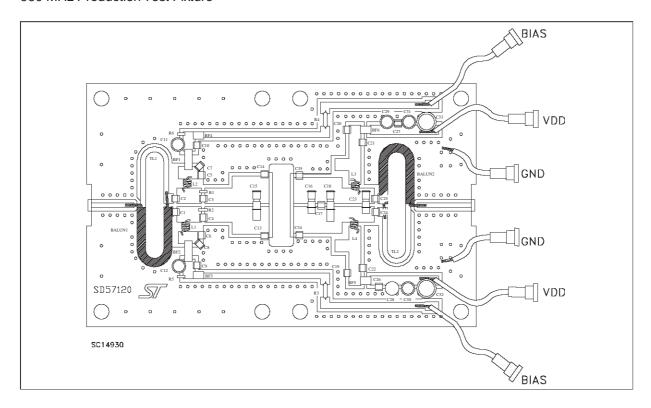


#### 960 MHz Test Circuit Component Part List

BF1-BF4	FAIR RITE PRODUCTS SHORT FERRIT BEAD 2743021447	
C1, C2, C24, C25	47pf	_
C3, C4,	42pf CHIP CAP	
C5, C6, C7, C8,	300pf CHIP CAP	
C19, C20, C21, C22,		
C9, C10	10000pf CHIP CAP	
C11, C12	10µf, 50V ELECTROLYTIC CAPACITOR	
C28, C29, C30, C31		
C13, C14, C17	1.7pf CHIP CAP	
C15, C18,	.8-8pf VARIABLE CAPACITOR	
C16, C23,	.6-4.5pf VARIABLE CAPACITOR	
C26, C27,	20000pf CHIP CAP	
C32, C33	220µf, 50V ELECTROLYTIC CAPACITOR	
C34, C35	5.6pf CHIP CAP	
BALUN1,BALUN2	2.2,50 Ω, .086" D.D. SEMI - RIGID COAX	
L1, L2, L3, L4	3 TURNS, #20AWG, IDIA 0.126", 24.7nH	
N1, N2	TYPE N CONNECTOR	
R1, R2	75Ω,	
R3, R4	1K Ω,	
R5, R6	1.2ΚΩ,	
T1, T2	50 Ω, TRANSMITION LINE	
B□ARD	30mil GLASS TEFLON $\mathcal{E}_r$ = 2.55	
COMPONENT	DESCRIPTION	

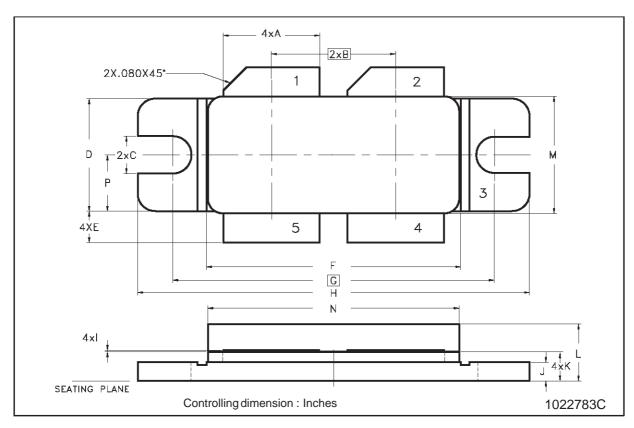
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#### 960 MHz Production Test Fixture



# M252 (.400 X .800 4L BAL N/HERM W/FLG) MECHANICAL DATA

DIM.		mm			inch	
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А	8.13		8.64	0.320		0.340
В		10.80			0.425	
С	3.00		3.30	0.118		0.130
D	9.65		9.91	0.380		0.390
Е	2.16		2.92	0.085		0.115
F	21.97		22.23	0.865		0.875
G		27.94			1.100	
Н	33.91		34.16	1.335		1.345
I	0.10		0.15	0.004		0.006
J	1.52		1.78	0.060		0.070
K	2.36		2.74	0.093		0.108
L	4.57		5.33	0.180		0.210
М	9.96		10.34	0.392		0.407
N	21.64		22.05	0.852		0.868



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